



PATENTS

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5-21-02*

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of

Hirokazu HONDA

Serial No. 09/678,609

GROUP 2827

Filed October 4, 2000

MULTILAYER INTERCONNECTION BOARD,  
SEMICONDUCTOR DEVICE HAVING THE SAME,  
AND METHOD OF FORMING THE SAME AS WELL  
AS METHOD OF MOUNTING THE SEMICONDUCTOR  
CHIP ON THE INTERCONNECTION BOARD

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**INFORMATION DISCLOSURE STATEMENT**

Commissioner for Patents

Washington, D.C. 20231

Sir:

In compliance with Rules 1.97 and 1.98, and in fulfillment of the duty of disclosure under Rule 1.56, the accompanying documents, copies of which are attached to this statement, are made of record on the enclosed sheet.

A concise explanation of the relevance of these items is that these references were cited by the Japanese Patent Office in an Office Action, a copy of which is attached hereto. An English translation of the portion enclosed in a wavy line is also attached hereto for the Examiner's convenience.

Under the provisions of 37 CFR 1.97(e), the undersigned hereby certifies that each item of information contained in this Information Disclosure Statement was cited in a communication from a foreign Patent Office in a counterpart

HONDA S.N. 09/678,609

foreign application not more than three months prior to the  
filing of this Statement.

Respectfully submitted,

YOUNG & THOMPSON

By



Robert J. Patch  
Attorney for Applicant  
Registration No. 17,355  
745 South 23rd Street  
Arlington, VA 22202  
Telephone: 703/521-2297

REG. NO.  
32,925  
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May 7, 2002